



Customer Information Notification

2013070201

Issue Date: 03-Aug-2013
Effective Date: 19-Aug-2013

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QUALITY

Management Summary

Microcontroller products LPC213x will have an updated bootloader version 2.14.

Change Category

Wafer Fab process	Assembly Process	Product Marking	Design
Wafer Fab materials	Assembly Materials	Electrical spec./Test coverage	Mechanical Specification
Wafer Fab location	Assembly Location	Test Location	Packing/Shipping/Labeling

Microcontroller products LPC213x will have an updated bootloader version 2.14

Information Notification

The bootloader on microcontroller products LPC213x has been updated from version 2.13 to 2.14.

Why do we issue this Information Notification

The bootloader update version 2.14 addresses a flash programming issue on the LPC213x devices. Under certain conditions at cold temperature (< 0C), the user flash memory contents may get corrupted during flash programming process (IAP or ISP commands) due to an insufficient settling time parameter for the data latches. At -40C (worst case temperature), this issue has been observed in < 400ppm of devices. The issue was not observed at >0C. The reliability of the flash (retention and endurance) is not affected.

Updated Bootloader version 2.14 will allow sufficient settling time for the data latches during the flash programming process and will prevent the flash programming issue.

Identification of Affected Products

Products with datecode after 1333 will be updated with the new bootloader version 2.14.

Impact

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

The current bootloader on the devices (date codes wk1333 and before) can be updated in-system by executing the update utility. The update utility can be found on [lpcware.com](http://www.lpcware.com) under LPC2000 Tools: <http://www.lpcware.com/content/nxpfile/bootloader-update-ver-214-lpc213x-rev-f-and-lpc2157-rev-f>

Please contact NXP quality department for additional questions.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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